

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 2-14 and 18-72.

Listing of Claims:

1. (Original) A method of planarizing a microelectronic-device substrate assembly, comprising:

removing material from a substrate assembly by pressing the substrate assembly against a planarizing surface of a planarizing pad and moving the substrate assembly across the planarizing surface; and

replacing at least a portion of a used volume of planarizing solution on the planarizing surface with fresh planarizing solution by actively removing used planarizing solution from an accumulation zone on the planarizing surface adjacent to a planarizing zone on the planarizing surface with a removing unit other than solely the movement of the pad and depositing fresh planarizing solution onto the planarizing pad.

15. (Original) The method of claim 1 wherein removing material from the substrate assembly and replacing at least a portion of the used volume of planarizing solution occur contemporaneously to continuously planarize the substrate assembly.

16. (Original) The method of claim 15 wherein the planarizing pad has a plurality of holes in an accumulation zone, the holes extending through the planarizing pad from the planarizing surface, and the removing unit comprises a vacuum chamber operatively coupled to the holes, and wherein actively removing the used planarizing solution comprises sucking the used planarizing solution through the holes in the planarizing pad by drawing a vacuum in the vacuum chamber while the substrate is pressed against and moved across the planarizing surface.

17. (Original) The method of claim 15 wherein actively removing the used planarizing solution comprises wiping at least a portion of the used planarizing fluid from the planarizing pad while the substrate assembly is pressed against and moved across the planarizing surface.